

Absolute Maximum Ratings

Drain-to-Source Voltage -6V
 Gate-to-Source Voltage -6V
 Continuous Drain Current
 $T_A = 25^\circ\text{C}$ ($V_{GS} = 4.5\text{V}$) 1.8A
 $T_A = 100^\circ\text{C}$ ($V_{GS} = 4.5\text{V}$) 1.2A
 Total Power Dissipation
 $T_A = 25^\circ\text{C}$ 568mW
 $T_A = 100^\circ\text{C}$ 227mW
 Operating Junction Temperature -40°C to $+150^\circ\text{C}$
 Storage Temperature -55°C to $+150^\circ\text{C}$
 ESD Rating, **Note 2**

Operating Ratings

Thermal Resistance
 θ_{JA} 220°C/W
 θ_{JC} 130°C/W

Electrical Characteristics (Note 1)

Symbol	Parameter	Condition (Note 1)	Min	Typ	Max	Units
V_{GS}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = -250\mu\text{A}$	0.5		1.2	V
I_{GSS}	Gate-Body Leakage	$V_{DS} = 0\text{V}$, $V_{GS} = -4.5\text{V}$, Note 2, Note 3			1	μA
R_{GS}	Gate-Source Resistance	$V_{DS} = 0\text{V}$, $V_{GS} = -4.5\text{V}$, Note 2, Note 4	200	350	500	k Ω
C_{ISS}	Input Capacitance	$V_{GS} = 0\text{V}$, $V_{DS} = -5.5\text{V}$		600		pF
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -5.5\text{V}$, $V_{GS} = 0\text{V}$			1	μA
		$V_{DS} = -5.5\text{V}$, $V_{GS} = 0\text{V}$, $T_J = 85^\circ\text{C}$			5	μA
$R_{DS(ON)}$	Drain-Source On-Resistance	$V_{GS} = -4.5\text{V}$, $I_D = -100\text{mA}$		0.125	0.160	Ω
		$V_{GS} = -3.6\text{V}$, $I_D = -100\text{mA}$		0.135	0.180	Ω
		$V_{GS} = -2.5\text{V}$, $I_D = -100\text{mA}$		0.165	0.200	Ω
		$V_{GS} = -1.8\text{V}$, $I_D = -100\text{mA}$		0.225	0.320	Ω
g_{FS}	Forward Transconductance	$V_{DS} = -5.5\text{V}$, $I_D = -200\text{mA}$, Note 5		3		S

Note 1. $T_A = 25^\circ\text{C}$ unless noted. Substrate connected to source for all conditions.

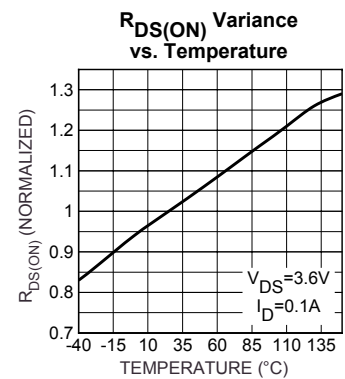
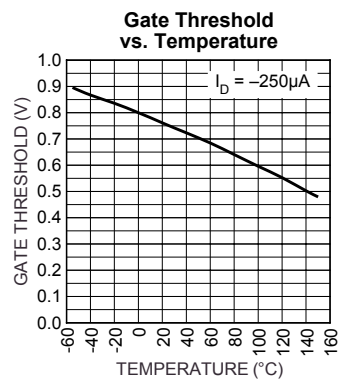
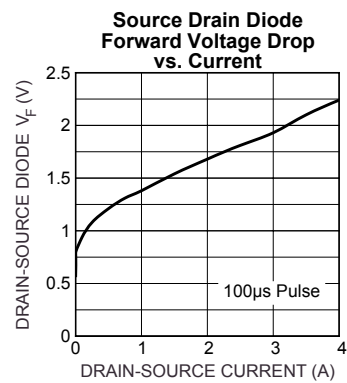
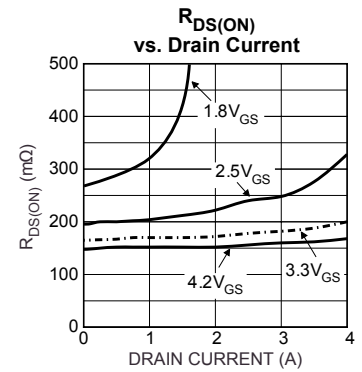
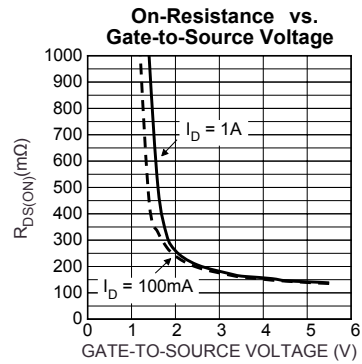
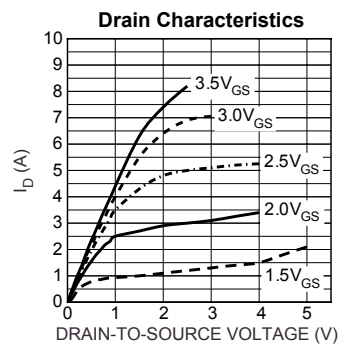
Note 2. ESD gate  precautions required

Note 3. MIC94050 only.

Note 4. MIC94051 only.

Note 5. Pulse Test: Pulse Width $\leq 80\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Typical Characteristics



Typical Applications

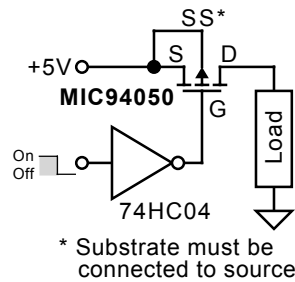


Figure 1. Load Switch Application

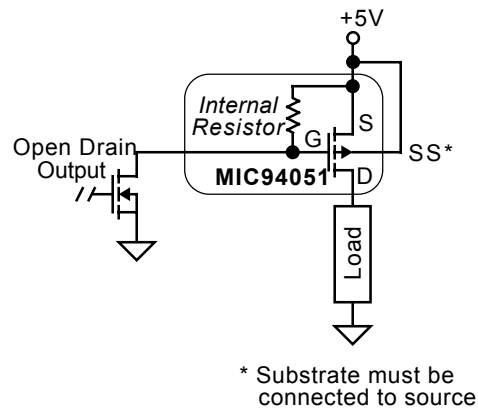


Figure 2. Load Switch Application
(with internal gate-source pull-up)

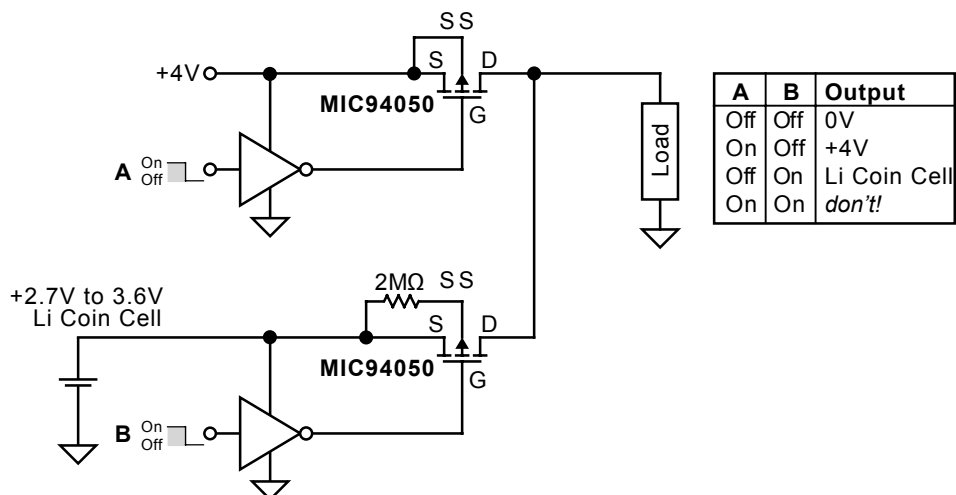
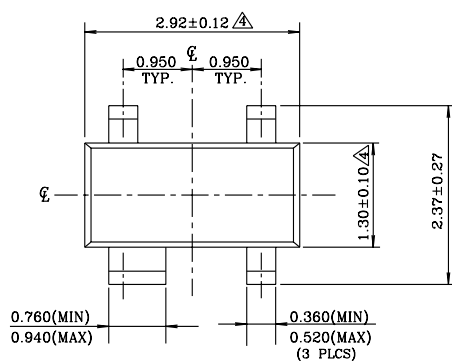
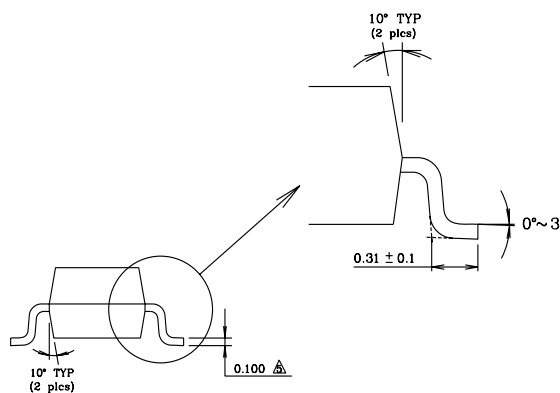


Figure 3. Reverse-Blocking Battery Back-Up Application

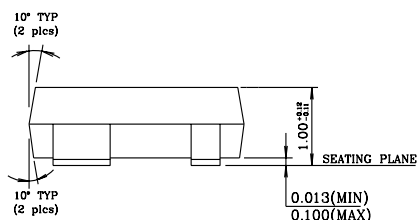
Package Information



TOP VIEW



END VIEW



SIDE VIEW

NOTE:

1. Dimensions and tolerances are as per ANSI Y14.5M, 1982.
 2. Package surface to be mirror finish.
 3. Die is facing up for mold & trim/form.
- △ Dimension are exclusive of mold flash and gate burr.
 △ Dimension are exclusive of solder plating.

SOT-143 (M4)

MICREL, INC. 2180 FORTUNE DRIVE SAN JOSE, CA 95131 USA

TEL + 1 (408) 944-0800 FAX + 1 (408) 474-1000 WEB <http://www.micrel.com>

The information furnished by Micrel in this data sheet is believed to be accurate and reliable. However, no responsibility is assumed by Micrel for its use. Micrel reserves the right to change circuitry and specifications at any time without notification to the customer.

Micrel Products are not □

reasonably be expected to result in personal injury. Life support devices or systems are devices or systems that (a) are intended for surgical implant into the body or (b) support or sustain life, and whose failure to perform can be reasonably expected to result in a significant injury to the user. A Purchaser's use or sale of Micrel Products for use in life support appliances, devices or systems is a Purchaser's own risk and Purchaser agrees to fully indemnify Micrel for any damages resulting from such use or sale.